

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 1 and cancel claim 17, as follows:

Listing of Claims:

1. (Currently Amended) A method of planarizing a microelectronic-device substrate assembly, comprising:

removing material from a substrate assembly by pressing the substrate assembly against a planarizing surface of a planarizing pad and moving the substrate assembly across the planarizing surface; and

replacing at least a portion of a used volume of planarizing solution on the planarizing surface with fresh planarizing solution by actively removing used planarizing solution from an accumulation zone on the planarizing surface adjacent to a planarizing zone on the planarizing surface with a removing unit other than solely the movement of the pad and depositing fresh planarizing solution onto the planarizing pad, wherein actively removing the used planarizing solution comprises wiping at least a portion of the used planarizing fluid from the planarizing pad while the substrate assembly is pressed against and moved across the planarizing surface.

2-14. (Cancelled)

15. (Original) The method of claim 1 wherein removing material from the substrate assembly and replacing at least a portion of the used volume of planarizing solution occur contemporaneously to continuously planarize the substrate assembly.

16. (Original) The method of claim 15 wherein the planarizing pad has a plurality of holes in an accumulation zone, the holes extending through the planarizing pad from the planarizing surface, and the removing unit comprises a vacuum chamber operatively coupled to the holes, and wherein actively removing the used planarizing solution comprises sucking the used planarizing solution through the holes in the planarizing pad by drawing a vacuum in the vacuum chamber while the substrate is pressed against and moved across the planarizing surface.

17-72. (Cancelled)